



# Lecol 5500 Parquet Adhesive

## Technical Data Sheet

### Water-free Synthetic Resin Adhesive

#### Product description

##### *General*

Lecol 5500 is a water-free synthetic resin adhesive.

##### *Properties*

To be used for laying mosaic and stick parquet as well as ready made parquet with high shear strength. Suitable for use on all properly prepared substrates. Lecol 5500 corresponds to the requirements of DIN 281.

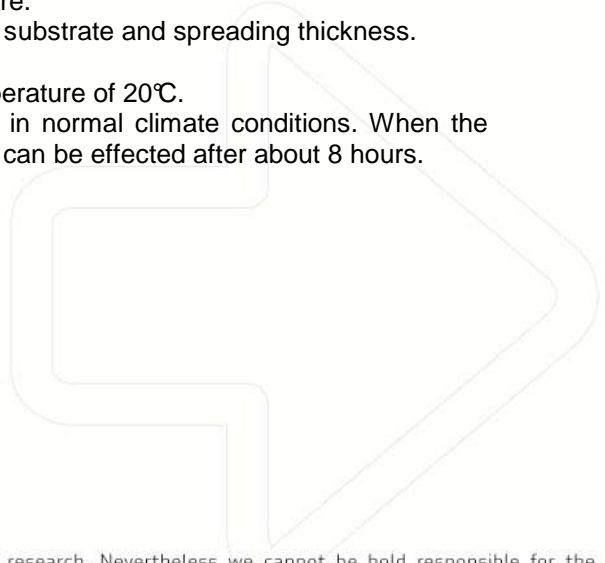
##### *Application*

With serrated trowel, for example TKB B2 (Pajarito C).

##### **Suitable for Wheelchair and floor heating**

#### Technical Data

Storage:	Not below + 5°C., susceptible to freezing . Approx. 6 months at room temperature.
Consumption:	about 700 - 900 g/m <sup>2</sup> , depending on substrate and spreading thickness.
Tool clean up:	Lecol K 50 thinners
Open time:	approx 5 to 10 minutes at room temperature of 20°C.
Drying time:	grindable after approx. 16-24 hours in normal climate conditions. When the substrate is very absorbent, grinding can be effected after about 8 hours.
Packaging:	6, 10 and 16 kg



This technical data sheet has been based on many years of experience and research. Nevertheless we cannot be held responsible for the manufactured work according to this recommendation, as eventual result is stipulated factors which fall outside our appraisal. We recommend you in any case carrying out own tests to examine if this product is suitable for the work you manufacture.



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### Sub floor

All substrates have to be prepared for parquet laying. Substrates must be totally dry, free from cracks, dirt, grease, oil, paint and adhesive residues. Substrates must be level and mechanically solid.

Cement composition floors corresponding to the norm and chipboards can generally be bonded without pre-treatment using Lecol 5500.

Anhydrite composition floors and other very absorbent, dusty and sandy substrates have to be primed with diluted adhesive (1 part Lecol 5500 + 1 part Lecol K50 thinners) or with diluted dispersion primer D3074.

Chip boards have to be nailed (screw nails) or screwed down; they are not allowed to move. Laying should be diagonal to the chipboard joints.

Levelling should possibly be avoided when laying mosaic parquet. However, if it should become necessary, Lecol synthetic resin cement levelling compound Z615 should be used with a thickness of 5 mm.

In this case, the substrate's solidity must be examined carefully to see whether it will withstand the tension which occurs with parquet.

Before levelling, cement composition floors have to be primed with Lecol Dispersion Primer D3074. Levelling may not be effected before the primer is completely dry.

Trials should be conducted in order to determine the levelling and bonding results prior to laying.

We do not recommend laying on magnesite composition floors and bitumen insulating coatings

### Instructions for use

Stir adhesive well before use. Apply evenly with a serrated Trowel to the substrate. Avoid adhesive lumps. Do not prepare more than about 1 m<sup>2</sup>. Fit the parquet in at once and press it down well. The back of the wood must have total contact with the adhesive. Expansion joints must be left at adjacent construction joints in the subfloor. On an absorbent subfloor in normal climate conditions and normal adhesive application. Sanding can take place after 16-24 hrs. On mastic asphalt and non absorbent subfloors, sanding should not take place until after 3 days. Do not apply below +15°C.

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### Underfloor heating

The heater should be in use at least 10 days prior to laying. Switch off 2 days prior to laying or reduce to a lower temperature in winter. Reheating can be effected slowly 3 days after laying

### Remarks

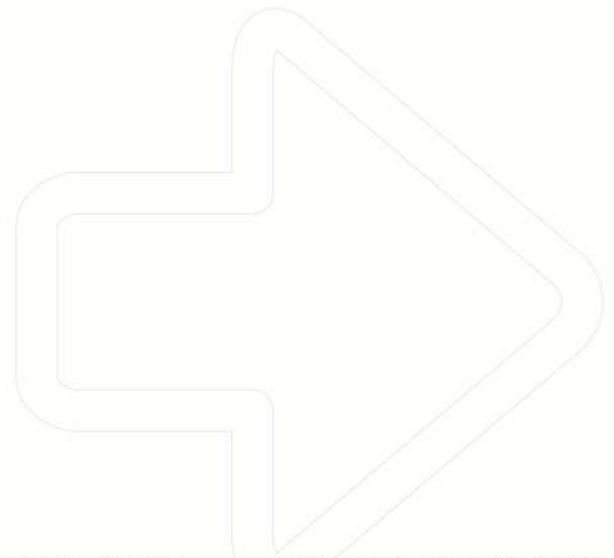
Do not apply adhesive at temperatures below +15°C. Successful layings of parquet floors have been effected at temperatures as low as +10°C. However, we can only guarantee a successful laying at temperatures of at least +15°C. Substrate, adhesive, parquet and room climate should possibly have the same temperatures. In the winter season, store parquet and adhesive beforehand in the room to be worked in. Do not lay parquet when having a very high humidity.

Apart from the information given in this leaflet please consult the manufacturing advice of the parquet producers and the valid standards and general working advice.

### Special Remarks

This technical datasheet supersedes all previous datasheets for this product.

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